TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE ($\pi$-MOSIII)

# 2SK2719

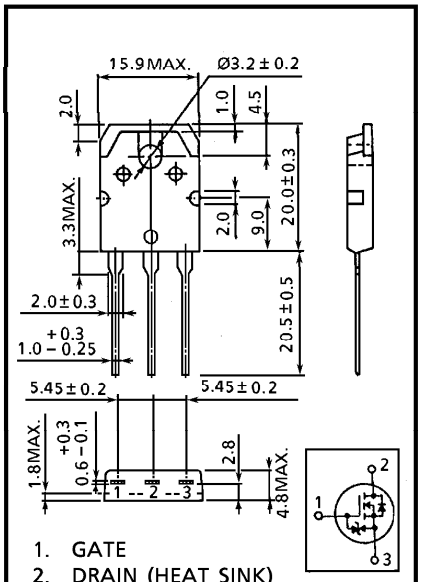
HIGH SPEED, HIGH VOLTAGE SWITCHING APPLICATIONS

CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE APPLICATIONS

INDUSTRIAL APPLICATIONS

- Low Drain-Sorce ON Resistance : $R_{DS\,(ON)} = 3.7\ \Omega$ (Typ.)
- High Forward Transfer Admittance : $|Y_{fs}| = 2.6$ S (Typ.)
- Low Leakage Current : $I_{DSS} = 100\ \mu$A (Max.) ($V_{DS} = 720$ V)
- Enhancement-Mode : $V_{th} = 2.0 \sim 4.0$ V ($V_{DS} = 10$ V, $I_D = 1$ mA)

Unit in mm




| | |
|---|---|
| JEDEC | — |
| EIAJ | SC-65 |
| TOSHIBA | 2-16C1B |

Weight : 4.6 g

MAXIMUM RATINGS (Ta = 25°C)

| CHARACTERISTIC | | SYMBOL | RATING | UNIT |
|---|---|---|---|---|
| Drain-Source Voltage | | $V_{DSS}$ | 900 | V |
| Drain-Gate Voltage ($R_{GS} = 20\ k\Omega$) | | $V_{DGR}$ | 900 | V |
| Gate-Source Voltage | | $V_{GSS}$ | ±30 | V |
| Drain Current | DC | $I_D$ | 3 | A |
| | Pulse | $I_{DP}$ | 9 | |
| Drain Power Dissipation (Tc = 25°C) | | $P_D$ | 125 | W |
| Single Pulse Avalanche Energy** | | $E_{AS}$ | 295 | mJ |
| Avalanche Current | | $I_{AR}$ | 3 | A |
| Repetitive Avalanche Energy* | | $E_{AR}$ | 12.5 | mJ |
| Channel Temperature | | $T_{ch}$ | 150 | °C |
| Storage Temperature Range | | $T_{stg}$ | −55~150 | °C |

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THERMAL CHARACTERISTICS

| CHARACTERISTIC | SYMBOL | MAX. | UNIT |
|---|---|---|---|
| Thermal Resistance, Channel to Case | $R_{th\ (ch\text{-}c)}$ | 1.0 | °C / W |
| Thermal Resistance, Channel to Ambient | $R_{th\ (ch\text{-}a)}$ | 50.0 | °C / W |

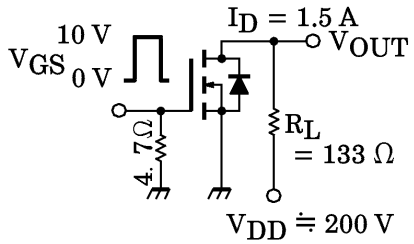
Note ;

* Repetitive rating ; Pulse Width Limited by Max. junction temperature.

** $V_{DD}$ = 90 V, $T_{ch}$ = 25°C (initial), L = 60 mH, $R_G$ = 25 Ω, $I_{AR}$ = 3 A

**This transistor is an electrostatic sensitive device.**
**Please handle with caution.**

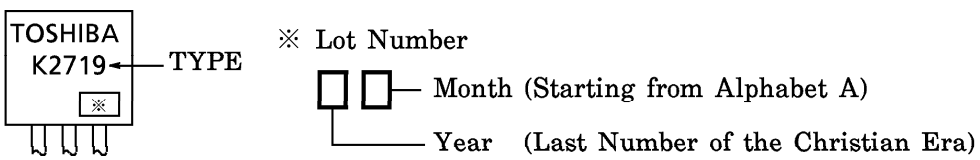
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

| CHARACTERISTIC | | SYMBOL | TEST CONDITION | MIN. | TYP. | MAX. | UNIT |
|---|---|---|---|---|---|---|---|
| Gate Leakage Current | | $I_{GSS}$ | $V_{GS}$ = ±30 V, $V_{DS}$ = 0 V | — | — | ±10 | μA |
| Gate-Source Breakdown Voltage | | $V_{(BR)\,GSS}$ | $I_G$ = ±10 μA, $V_{DS}$ = 0 V | ±30 | — | — | V |
| Drain Cut-off Current | | $I_{DSS}$ | $V_{DS}$ = 720 V, $V_{GS}$ = 0 V | — | — | 100 | μA |
| Drain-Source Breakdown Voltage | | $V_{(BR)\,DSS}$ | $I_D$ = 10 mA, $V_{GS}$ = 0 V | 900 | — | — | V |
| Gate Threshold Voltage | | $V_{th}$ | $V_{DS}$ = 10 V, $I_D$ = 1 mA | 2.0 | — | 4.0 | V |
| Drain-Source ON Resistance | | $R_{DS\,(ON)}$ | $V_{GS}$ = 10 V, $I_D$ = 1.5 A | — | 3.7 | 4.3 | Ω |
| Forward Transfer Admittance | | $\|Y_{fs}\|$ | $V_{DS}$ = 20 V, $I_D$ = 1.5 A | 0.65 | 2.6 | — | S |
| Input Capacitance | | $C_{iss}$ | $V_{DS}$ = 25 V, $V_{GS}$ = 0 V, f = 1 MHz | — | 750 | — | pF |
| Reverse Transfer Capacitance | | $C_{rss}$ | | — | 10 | — | |
| Output Capacitance | | $C_{oss}$ | | — | 70 | — | |
| Switching Time | Rise Time | $t_r$ |   $V_{IN}$ : $t_r$, $t_f$ < 5 ns, Duty ≦ 1%, $t_w$ = 10 μs | — | 15 | — | ns |
| | Turn-on Time | $t_{on}$ | | — | 55 | — | |
| | Fall Time | $t_f$ | | — | 30 | — | |
| | Turn-off Time | $t_{off}$ | | — | 110 | — | |
| Total Gate Charge (Gate-Source Plus Gate-Drain) | | $Q_g$ | $V_{DD}$ ≒ 400 V, $V_{GS}$ = 10 V, $I_D$ = 3 A | — | 25 | — | nC |
| Gate-Source Charge | | $Q_{gs}$ | | — | 13 | — | |
| Gate-Drain ("Miller") Charge | | $Q_{gd}$ | | — | 12 | — | |

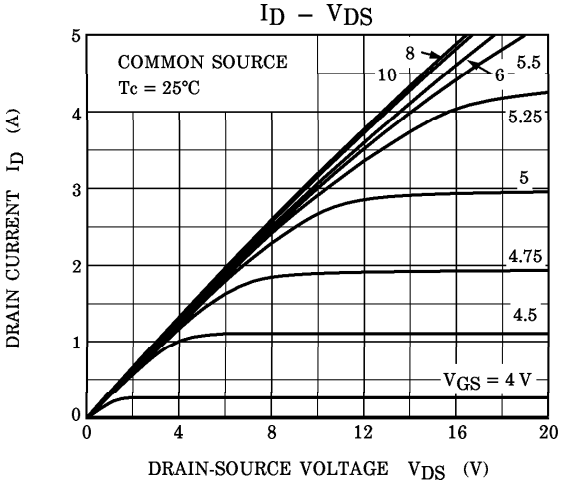
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

| CHARACTERISTIC | SYMBOL | TEST CONDITION | MIN. | TYP. | MAX. | UNIT |
|---|---|---|---|---|---|---|
| Continuous Drain Reverse Current | $I_{DR}$ | — | — | — | 3 | A |
| Pulse Drain Reverse Current | $I_{DRP}$ | — | — | — | 9 | A |
| Diode Forward Voltage | $V_{DSF}$ | $I_{DR}$ = 3 A, $V_{GS}$ = 0 V | — | — | −1.9 | V |
| Reverse Recovery Time | $t_{rr}$ | $I_{DR}$ = 3 A, $V_{GS}$ = 0 V | — | 1100 | — | ns |
| Reverse Recovery Charge | $Q_{rr}$ | $dI_{DR}$ / dt = 100 A / μs | — | 7.5 | — | μC |

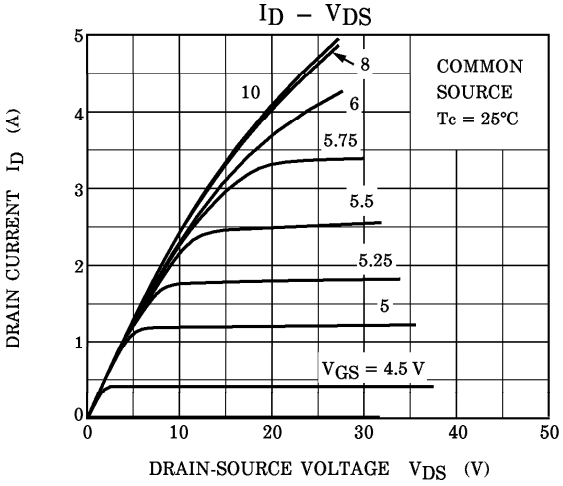
MARKING



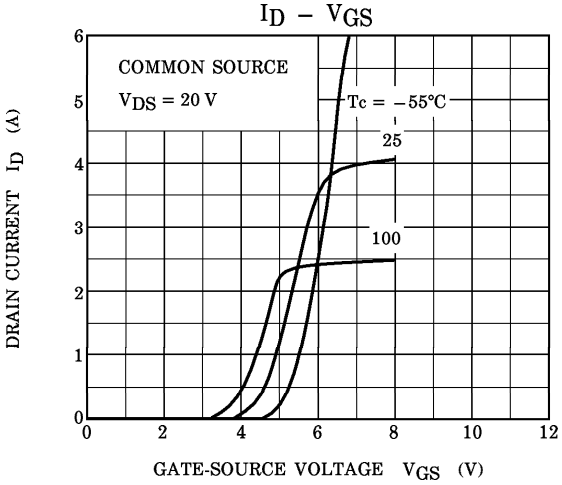
$I_D - V_{DS}$



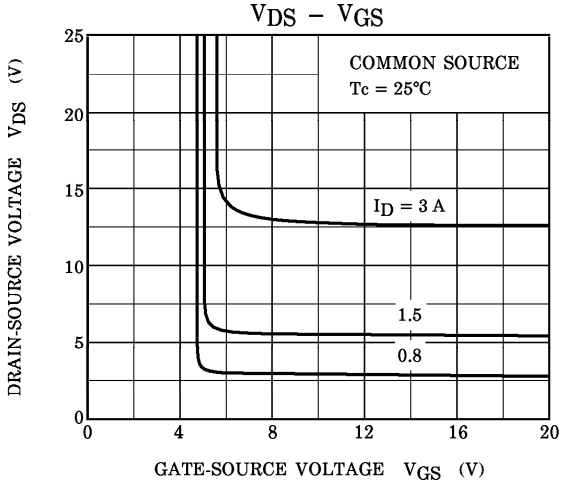

$I_D - V_{DS}$



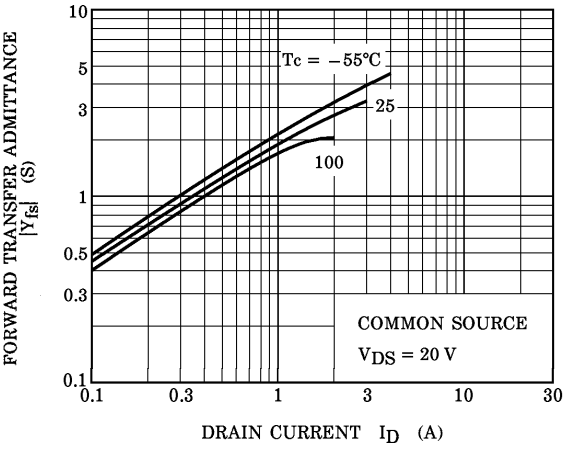

$I_D - V_{GS}$



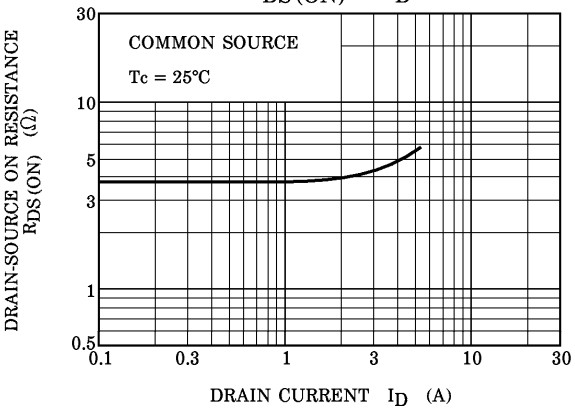

$V_{DS} - V_{GS}$



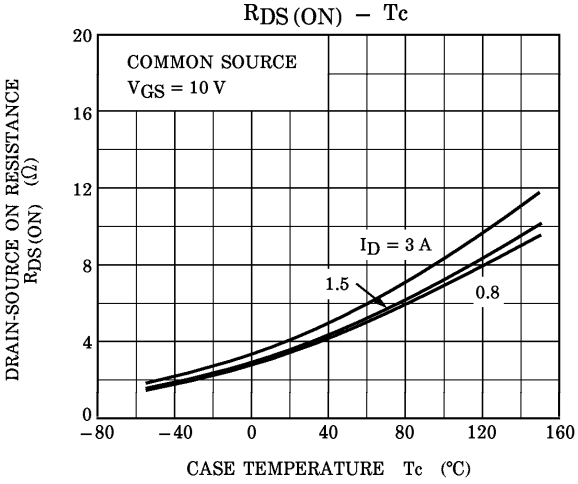

$|Y_{fs}| - I_D$



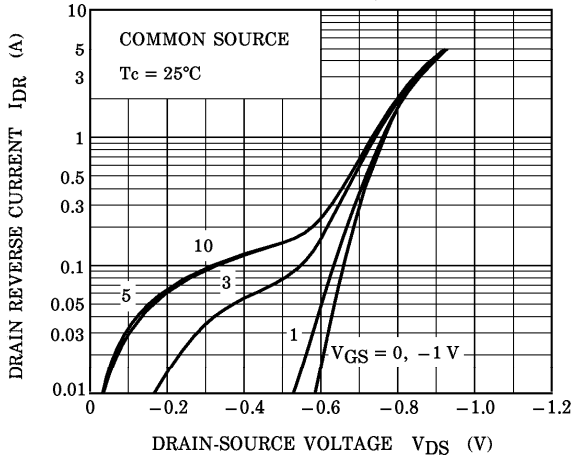

$R_{DS(ON)} - I_D$



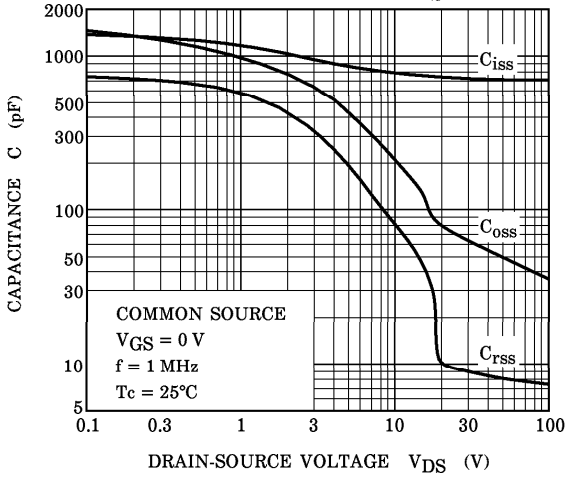
$R_{DS\,(ON)}$ – Tc



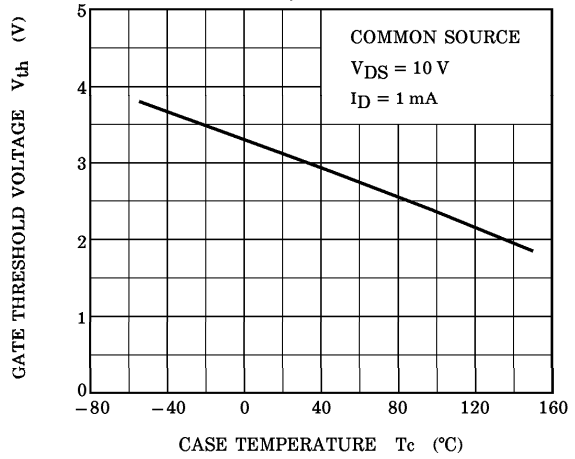

$I_{DR}$ – $V_{DS}$



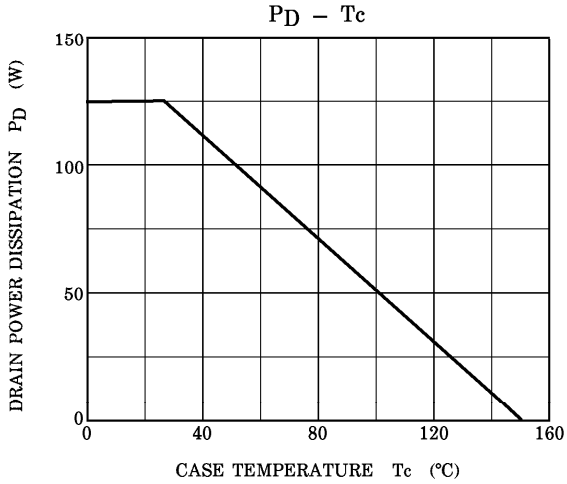

CAPACITANCE – $V_{DS}$



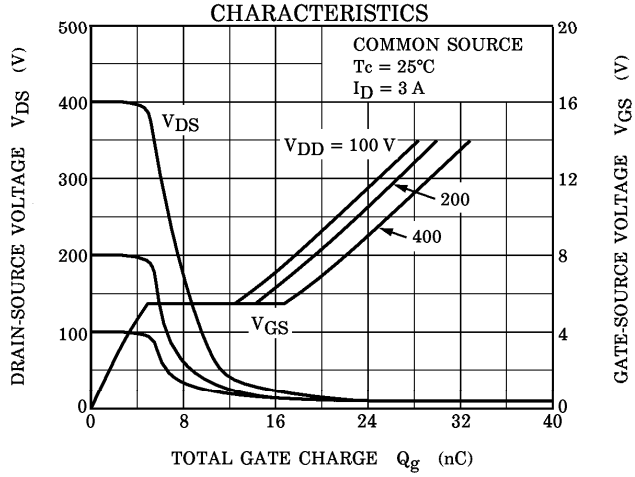

$V_{th}$ – Tc



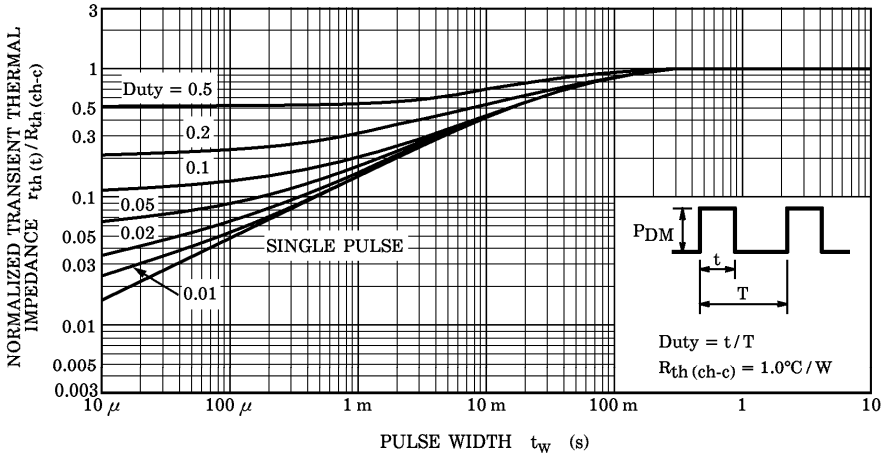

$P_D$ – Tc



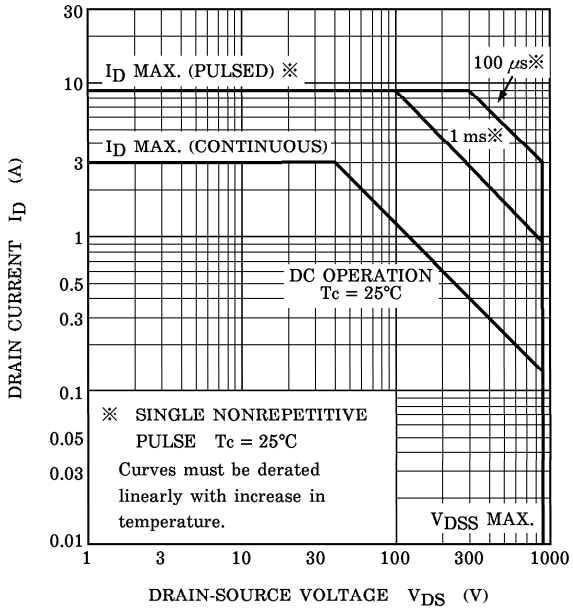

DYNAMIC INPUT / OUTPUT CHARACTERISTICS



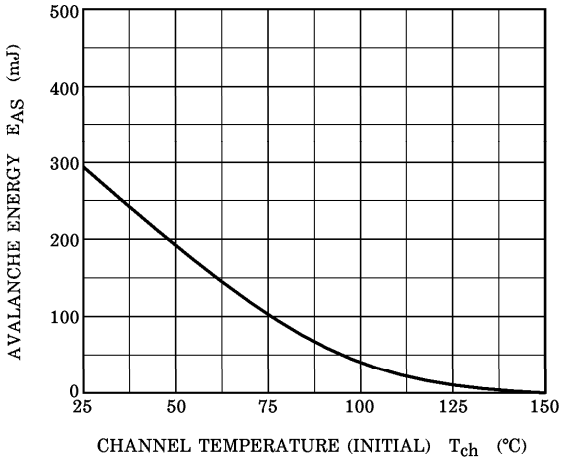
$r_{th}$ – $t_w$

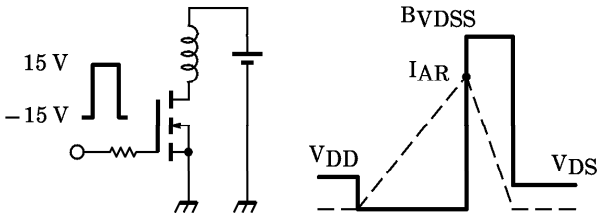



SAFE OPERATING AREA




$E_{AS}$ – $T_{ch}$




TEST CIRCUIT WAVE FORM

Peak $I_{AR}$ = 3 A, $R_G$ = 25 Ω
$V_{DD}$ = 90 V, L = 60 mH

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$